

	Type	L #	Hit s	Search Text	DBs
1	BRS	L1	374 9	wafer and (dice or chip) and etch\$4 and package	USPAT; EPO; JPO; IBM_TD B
2	IS&R	L2	113 9	((438/106) or (438/108) or (438/113)).CCLS.	USPAT
3	BRS	L3	200	1 and 2	USPAT; EPO; JPO; IBM_TD B
4	BRS	L6	1	"5998232".PN.	USPAT
5	BRS	L7	143 25	(dice or chip) same etch\$4	USPAT; EPO; JPO; IBM_TD B
6	BRS	L8	260	2 and 7	USPAT; EPO; JPO; IBM_TD B
7	BRS	L10	1	"5895581".PN.	USPAT
8	IS&R	L12	614	(438/106).CCLS.	USPAT
9	BRS	L15	472 2	die same etch\$4	USPAT; EPO; JPO; IBM_TD B
10	BRS	L16	126	2 and 15	USPAT; EPO; JPO; IBM_TD B
11	BRS	L17	241 6	die and etch\$4 and chip and carrier	USPAT; EPO; JPO; IBM_TD B

	Type	L #	Hit s	Search Text	DBs
12	BRS	L18	107	17 and 2	USPAT; EPO; JPO; IBM_TD B
13	BRS	L19	1	"5611140".PN.	USPAT